

Title (en)
Flexible printed substrate.

Title (de)
Biegsamer gedruckter Substrat.

Title (fr)
Substrat imprimé flexible.

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- JP 12116792 A 19920414
- JP 12417492 A 19920415
- JP 12953892 A 19920421
- JP 16039392 A 19920526
- JP 17467192 A 19920602
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- JP 26887291 A 19910919
- JP 33755691 A 19911126
- JP 33755791 A 19911126

Abstract (en)
A flexible printed substrate imparted with an adhesive property for loading on an external substrate, a double printed substrate having formed on both surfaces thereof a metal layer or a wiring circuit, and a multilayer substrate having a multilayer structure are disclosed. The flexible printed substrate comprises an insulating resin layer comprising a low-linear expansion polyimide resin layer and a thermoplastic polyimide resin layer, and a metal layer or a wiring circuit formed on the low-linear expansion polyimide resin layer of the insulating resin layer, wherein a mixed region of the polyimide resin components is formed in the interface between the low-linear expansion polyimide resin layer and the thermoplastic polyimide resin layer. <IMAGE>

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IPC 8 full level
H05K 1/03 (2006.01); **H05K 3/20** (2006.01); **H05K 3/28** (2006.01); **H05K 3/40** (2006.01); **H05K 3/42** (2006.01); **H05K 3/46** (2006.01); **H05K 1/00** (2006.01); **H05K 3/00** (2006.01)

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H05K 1/036 (2013.01 - EP US); **H05K 3/205** (2013.01 - EP US); **H05K 3/281** (2013.01 - EP US); **H05K 3/4007** (2013.01 - EP US); **H05K 3/421** (2013.01 - EP US); **H05K 3/4617** (2013.01 - EP US); **H05K 3/4632** (2013.01 - EP US); **H05K 3/4635** (2013.01 - EP US); **H01L 2224/32225** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - EP US); **H05K 1/0346** (2013.01 - EP US); **H05K 1/0393** (2013.01 - EP US); **H05K 3/0035** (2013.01 - EP US); **H05K 3/28** (2013.01 - EP US); **H05K 3/423** (2013.01 - EP US); **H05K 3/427** (2013.01 - EP US); **H05K 3/4647** (2013.01 - EP US); **H05K 2201/0129** (2013.01 - EP US); **H05K 2201/0154** (2013.01 - EP US); **H05K 2201/0195** (2013.01 - EP US); **H05K 2201/0347** (2013.01 - EP US); **H05K 2201/0355** (2013.01 - EP US); **H05K 2201/0358** (2013.01 - EP US); **H05K 2201/0367** (2013.01 - EP US); **H05K 2201/0394** (2013.01 - EP US); **H05K 2201/068** (2013.01 - EP US); **H05K 2201/09481** (2013.01 - EP US); **H05K 2201/10378** (2013.01 - EP US); **H05K 2203/0152** (2013.01 - EP US); **H05K 2203/0156** (2013.01 - EP US); **H05K 2203/0376** (2013.01 - EP US); **H05K 2203/063** (2013.01 - EP US); **H05K 2203/0726** (2013.01 - EP US); **H05K 2203/0733** (2013.01 - EP US); **H05K 2203/107** (2013.01 - EP US); **H05K 2203/1572** (2013.01 - EP US); **Y10S 428/901** (2013.01 - EP US); **Y10T 428/24917** (2015.01 - EP US); **Y10T 428/24942** (2015.01 - EP US); **Y10T 428/31721** (2015.04 - EP US)

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